

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Qing Ma

Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER STRUCTURE

Docket No.: 884.803US2

Serial No.: 10/774,923

Filed: February 9, 2004

Due Date: April 13, 2005

Examiner: Roy K. Potter

Group Art Unit: 2822

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

☒ A return postcard.

☒ An Amendment and Response Under 37 C.F.R. 1.111 (10 Pages).

If not provided for in a separate paper filed herewith, Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: Ann M. McCrackin
Atty: Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 14th day of March, 2005.

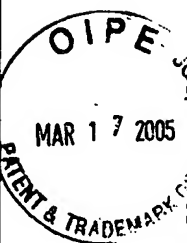
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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)

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S/N 10/774,923

PATENT

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Applicant:	Qing Ma	Examiner:	Roy K. Potter
Serial No.:	10/774,923	Group Art Unit:	2822
Filed:	February 9, 2004	Docket No.:	884.803US2
Title:	DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER STRUCTURE		
Assignee:	Intel Corporation	Customer No:	21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
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Alexandria, VA 22313-1450

PRELIMINARY REMARKS

Applicant gratefully acknowledges the provisional indication of allowability of several of the claims.

This responds to the Office Action mailed on January 13, 2005. Please amend the above-identified patent application as follows.